

#3 1/2
A
1/28/00

IN THE UNITED STATES PATENT AND
TRADEMARK OFFICE

PATENT

Applicant(s): Misuo Sugiyama; Hatsuyuki Arai

Docket No.: 30598.0004

Reissue of 5,605,499
Patent No.:

Application No.: 08/421,706

Issued: February 25, 1997

Filed: April 13, 1995

Title: FLATTENING METHOD AND
FLATTENING APPARATUS OF A
SEMICONDUCTOR DEVICE

Examiner: Andrew Weinberg

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination of the captioned reissue application, please amend the application as follows:

In the Claims

Rewrite claim 1 as follows:

1. (Amended) A flattening method of a semiconductor device by a chemical-mechanical polishing process comprising,
preparing a synthetic resin polishing cloth in a circular form and a tool for forming a surface layer of the synthetic resin polishing cloth to have fluff thereon in a polishing process, said tool having an annular shape with a diameter less than a radial length of the polishing cloth, and